

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7847542

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JI YOUNG LEE	01/18/2023
BYUNG MIN YU	01/18/2023
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	EM-TECH CO., LTD.
<b>Street Address:</b>	40 CHANGWONDAERO 1144 BEON-GIL, SEONGSAN-GU
<b>Internal Address:</b>	CHANGWON-SI
<b>City:</b>	GYEONGSANGNAM-DO
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	51539
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17986979
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	official@mbhiplaw.com
<b>Correspondent Name:</b>	MURPHY, BILAK & HOMILLER, PLLC
<b>Address Line 1:</b>	PO BOX 1959
<b>Address Line 4:</b>	CARY, NORTH CAROLINA 27572-1959
<b>ATTORNEY DOCKET NUMBER:</b>	1050-0139 / FP22266/US
<b>NAME OF SUBMITTER:</b>	MARK R. BILAK
<b>SIGNATURE:</b>	/Mark R. Bilak, Reg. No. 47,423/
<b>DATE SIGNED:</b>	03/15/2023
<b>Total Attachments: 2</b>	
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source=1050-0139 Assignment - signed#page2.tif	

## ASSIGNMENT

This Assignment is made by:

**Ji Young Lee**

**307-703, Yulha 2-ro, Gimhae-si  
Gyeongsangnam-do, 51019  
Republic of Korea**

**Byung Min Yu**

**103-506, 38, Sindaebang 1ga-gil, Dongjak-gu  
Seoul, 07072  
Republic of Korea**

hereinafter individually or collectively referred to as "Assignor";

hereby sell, assign and transfer to **EM-TECH Co., Ltd.**, having its principal place of business at

40 Changwondaero 1144 beon-gil, Seongsan-gu  
Changwon-si

Gyeongsangnam-do, 51539  
Republic of Korea

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on: Nov 15, 2022 as US Serial No: 17/986,979

entitled: Diaphragm for High Pressure Waterproof Microspeaker and High Pressure  
Waterproof Microspeaker Including the Same

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

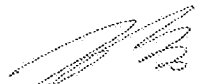
**PATENT**

**REEL: 062990 FRAME: 0515**

# ASSIGNMENT

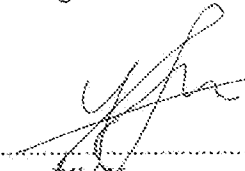
Date 23. 01. 18

Signature of Assignor

  
.....  
Ji Young Lee

Date 23. 01. 18

Signature of Assignor

  
.....  
Byung Min Yu